

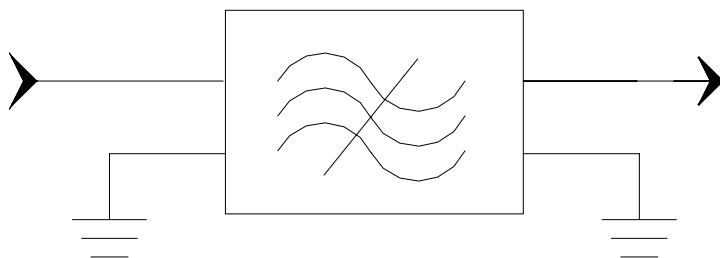
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	159.9	160	160.1
Insertion Loss	dB		24.5	26.5
3 dB Bandwidth	MHz	26.1	26.2	
40 dB Bandwidth	MHz		28.8	28.9
Passband Variation	dB		1	1.2
Ultimate Rejection	dB	48	50	
Absolute delay	usec		1.4	
Material Temperature coefficient	KHz/°C	-13.12		
Ambient Temperature	°C	25		
Package Size	DIP2712 (27.0x12.8x4.7mm ³)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance shown

Matching Configuration



Source/Load Impedance=50 ohm

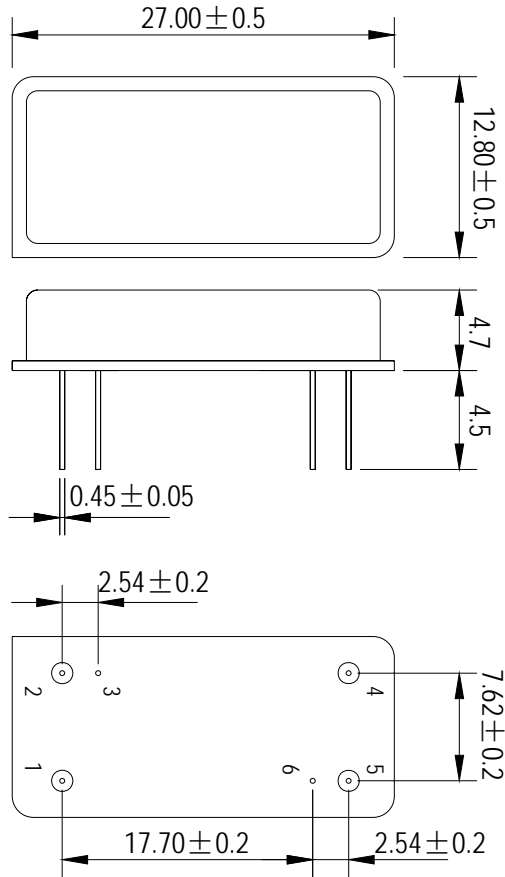
Notes - Component values may change depending on board layout.



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Part Number	SP LBN16026		
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Package Dimension



Input:1
Output:5

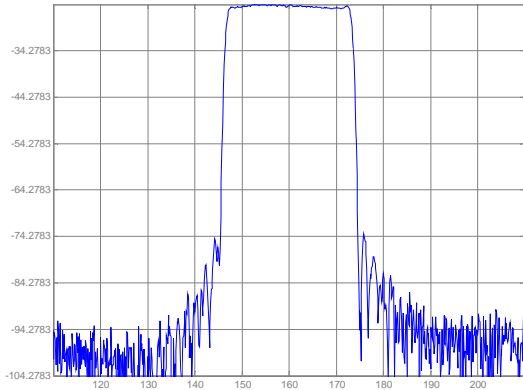


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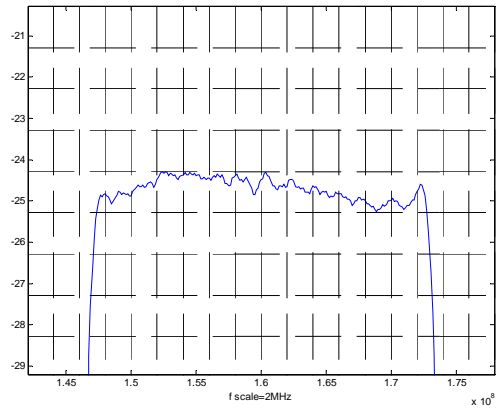
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Typical Performance

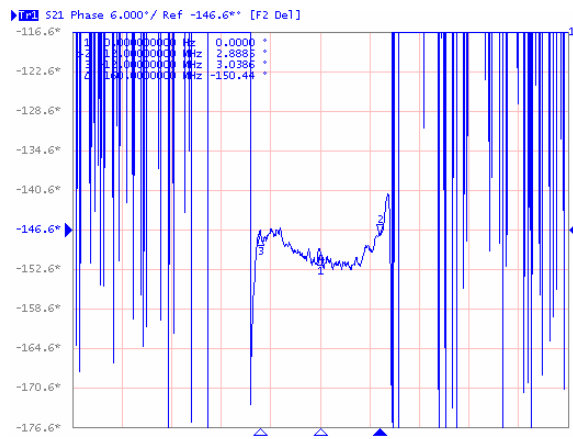
Frequency Response



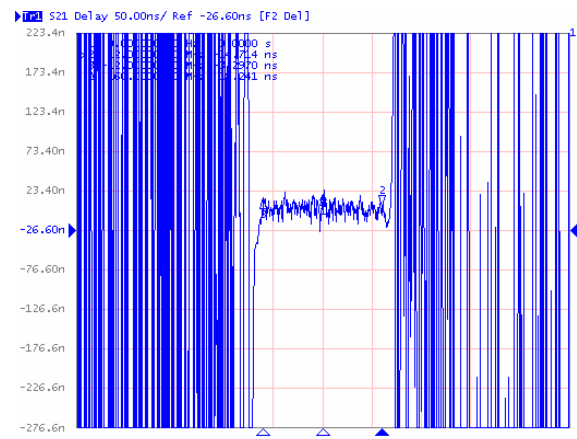
Passband Response



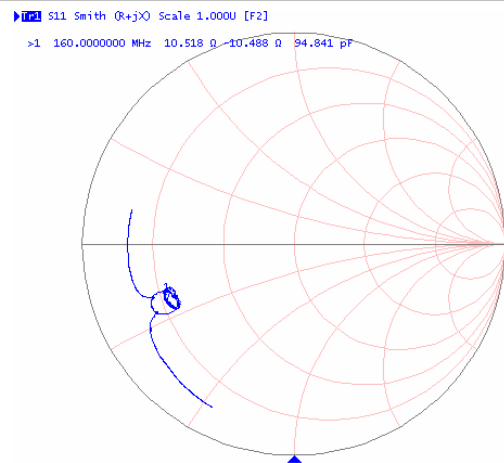
Phase Linearity($f_0 \pm 12\text{MHz}$)



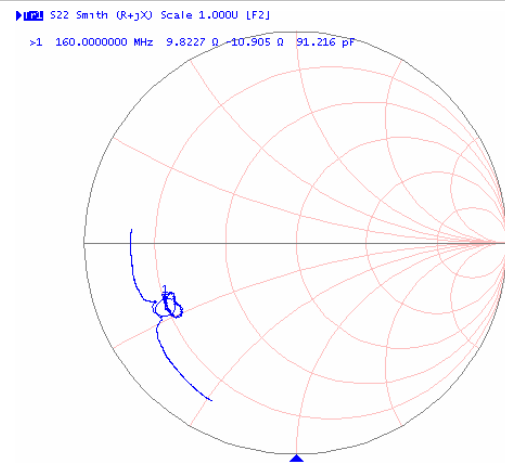
Group delay Variation($f_0 \pm 12\text{MHz}$)



Smith Chart S11



Smith Chart S22



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